CBC2 testing status

CMS Tk phase II electronics meeting – April 16th, 2013

since last time

have concentrated on wire-bond setup

learn as much as possible about CBC2 performance with this non-optimal bonding setup

objective to develop further and refine chip setup and evaluation software procedures

relevant to wafer probe test for remaining wafers



analogue mux



gives access to bias levels for diagnostic purposes

most useful for bias voltages (e.g. comparator threshold), bandgap

not so useful for currents - actually looking at current mirror outputs

future for this?

could be used to feed on-chip slow ADC in CBC3 not clear how useful this ADC would be may decide to just keep mux output to be used during probe test



I2C value



LDO performance



LDO

load currents 40, 60, 80 mA dropouts ~ 30, 55, 70 mV (approx.)

DC shift due to series resistance

50 mOhm on-chip + wire-bond resistance (which will go away when bump-bonded)

other power related measurements

measured band-gap voltage: 0.604 (for this chip) quiescent power consumption from VDDD all bias currents set to zero, SLVS off ~4.4mA all bias currents set to zero, SLVS ON ~6.7mA



2 significant problems

postamp: VPAFB susceptible to CM effects needed external decoupling for stability

comparator: VCTH affected by external hysteresis network external overdriving solved the problem

also input test pulse caps there, but no on-chip circuit to drive



VPAFB buffered by source follower on every channel





VPAFB controls back edge of postamp O/P pulse shape



comparator CBC1 vs. CBC2

HYSTERESIS CIRCUIT on CBC1





new comparator uses internally generated hysteresis - no load on VCTH

but so far have not found it necessary to use hysteresis anyway

CBC1 or CBC2

on-chip test pulse

figure from CBC2 manual



on-chip test pulse

figure from CBC2 manual

test pulse amplitude provided by resistor string between 1.1V & GND 256 steps

charge inject polarity depends on which switch closed

charge injected into 32 channels simultaneously through 20 fF caps

20fF largest source of uncertainty

20fF x (1.1V / 256) = 0.086 fC step resolution

e.g. value of 12 corresponds to \sim 1 fC (+/- 10%)



test pulse sweep

sweeping charge injection time allows to study comparator behaviour

count the number of times hit observed for fixed number of triggers, for each timestep

get coarse steps of 25 nsec by moving test trigger fast control pulse

get 1 nsec resolution using DLL steps

hysteresis circuit working as expected (note: new method of implementing in CBC2)



post-amp feedback resistor control

can see effect of VPAFB using test pulse sweep - smaller values give shorter pulse length

hit detect circuit works - only single hit in pipeline irrespective of how long comp O/P stays high

~ 2 fC signal

~ 1 fC comp. thresh



pulse length vs. amplitude

ideally (to address dead-time issue) want comparator high for less than 50 ns

not case for signals $> \sim 2$ fC

=> can study dead-time vs. pulse length using CBC2 but postamp feedback FET will probably need tweaking for CBC3

note: all plots contain 254 channels data 10 fC plot shows activity in channels not being driven by test pulse

crosstalk? power supply disturbance?



TP charge injection time [nsec]



s-curve skew

s-curve mid-points obtained by fitting raw data with erfc function

value gets skewed by non-linearity of VCTH

not a big problem, but worth trying to improve



gain - electrons mode





early conclusion still stands

"CBC2 working well enough to allow progress with module development"

only minor problems/inconveniences identified so far

test pulse DLL occasionally loses lock VCTH differential non-linearity evidence of crosstalk for high test pulse amplitudes

better to study further on bump-bonded setup

future for wire-bonded chip setup

now ready to refine wafer probe procedure

could be useful for ionising radiation studies using X-rays

extra

verifying functionality with test pulse



arrangement of 8 groups of test pulse connections allows to simulate signals from different layers and therefore exercise correlation logic

e.g. channels 1 & 2, or 17 & 18 would originate in different layers

can also verify correlation window width using channel mask register and window offset

e.g. mask all channels except 1 and 18 and use wide window (correlate channel 1 on layer 1 with channel 9 on layer 2)

note: can only use one test group at a time

cannot exercise CWD logic

first result



S-curves and tuning



254 offset values after tuning

